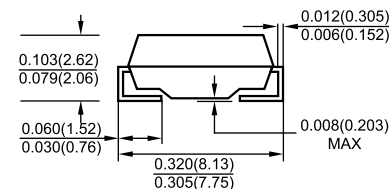
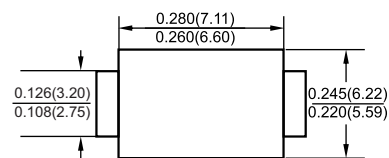


### FEATURES

- Voltage range 50~1000 volts
- Low forward voltage drop
- Low profile package
- High surge current capability
- Built-in strain relief
- Fast recovery time
- Epitaxial construction
- High temperature soldering:  
250°C /10 seconds at terminals

### MECHANICAL DATA

- Case Material: Molded Plastic, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 Per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish), Solderable MIL-STD-202, Method 208
- Polarity: Cathode Band or Cathode Notch
- Weight: SMC - 0.211 grams



SMC / DO-214AB  
Dimensions in inches and (millimeters)

### MAXIMUM RATINGS & THERMAL CHARACTERISTICS

Parameter	Symbol	RS3A	RS3B	RS3D	RS3G	RS3J	RS3K	RS3M	Unit
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @ T <sub>a</sub> = 50°C	I <sub>F(AV)</sub>	3.0							A
Peak Forward Surge (Non-Repetitive) Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	I <sub>FSM</sub>	100							A
Maximum Instantaneous Forward Voltage @ 3.0A	V <sub>FM</sub>	1.3							V
Maximum DC Reverse Current @ T <sub>A</sub> = 25°C At rated DC blocking voltage @ T <sub>A</sub> = 125°C	I <sub>RRM1</sub> I <sub>RRM2</sub>	5 250							μA
Reverse Recovery Time (Note 1)	T <sub>RR</sub>	150				250	500		ns
Typical Junction Capacitance (Note 2)	C <sub>J</sub>	50							pF
Junction Thermal Resistance (Note 3)	R <sub>θJA</sub> R <sub>θJL</sub>	10 50							°C / W
Operating Temperature Range	T <sub>J</sub>	-55 to +150							°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150							°C

**NOTE:** 1. Reverse Recovery Test conditions: I<sub>F</sub> = 0.5A, I<sub>R</sub> = 1.0A, I<sub>RR</sub> = 0.25A.  
2. Measured at 1.0 MHz and applied reverse voltage of 4.0 VDC.  
3. R<sub>θJA</sub> - Thermal Resistance Junction to Lead; R<sub>θJL</sub> - Thermal Resistance Junction to Ambient

**PACKAGING INFORMATION**

FIG.1-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

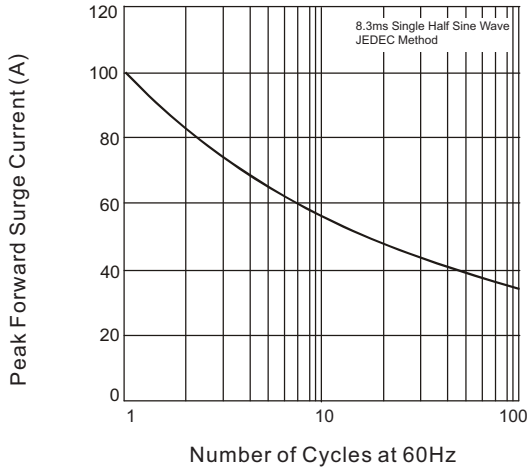


FIG.2-MAXIMUM CURRENT DERATING CURVE

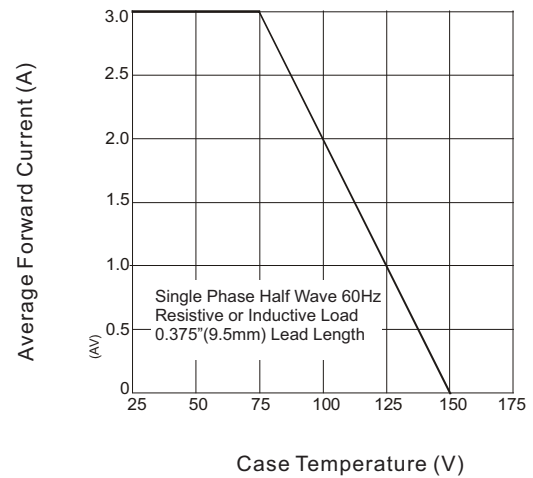


FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

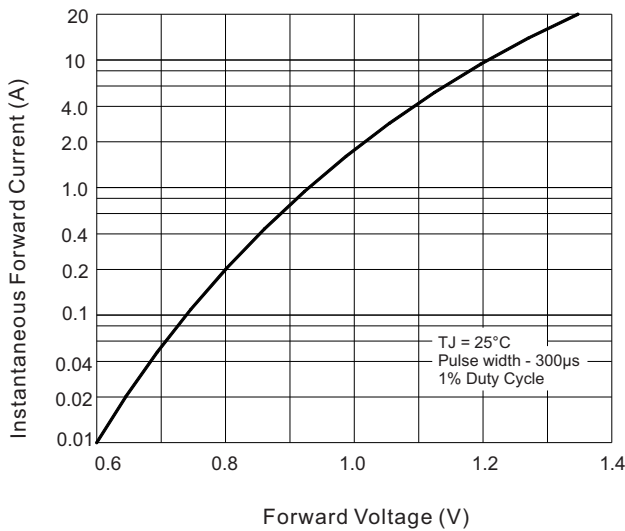


FIG.4-TYPICAL REVERSE CHARACTERISTICS

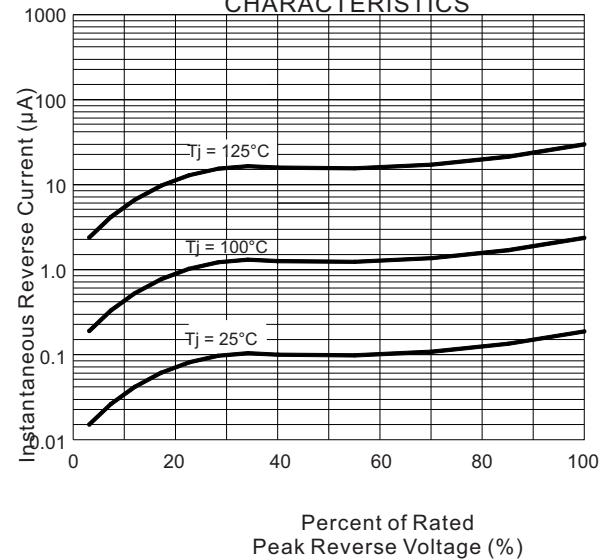
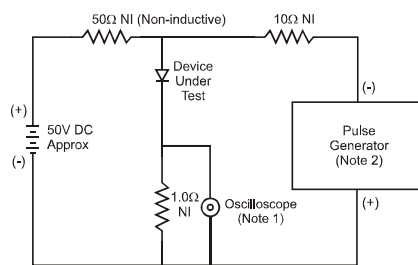


FIG.5-REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT



Notes:  
1. Rise Time = 7.0ns max. Input Impedance = 1.0MΩ, 22pF.  
2. Rise Time = 10ns max. Input Impedance = 50Ω.

